

Overview

The Spartan™-3 family of products will be manufactured at the UMC 300 mm wafer fabrication facility.

Description

Starting in 2005, the Spartan-3 family of devices will be manufactured at UMC's 300 mm wafer fabrication facility, a world-class, fully operational manufacturing plant with proven capability at 90 nm. The 90 nm process for Spartan-3 devices on 300 mm wafers is pin, function, timing, and programming file compatible with the existing 90 nm process for Spartan-3 devices on 200 mm wafers. All other key features, such as power supply voltage, number of metallization layers, and JTAG IDCODE, remain unchanged. Xilinx initiated this change to improve effective and competitive product support and to accommodate our customers' high-volume demand.

Products Affected

All members of the Spartan-3 product family will be manufactured at the 300 mm wafer facility. These include the XC3S50, XC3S200, XC3S400, XC3S1000, and XC3S1500 devices, which are currently manufactured at the UMC 200 mm wafer facility. Remaining members of the Spartan-3 product family not listed in this PCN are unaffected.

A special ordering number, SCD0974, must be used by customers who want to receive material manufactured only at the 300 mm wafer facility. To use SCD0974, append 0974 to the end of the standard ordering part number (e.g., XC3S50-4VQ100C0974). The SCD number will not be marked on the top of the package.

Key Dates

Qualification samples of the UMC 300 mm fabrication facility are now available, and initial production shipment is scheduled for August 1, 2005. Starting on the initial production shipment date, customers can receive Spartan-3 devices manufactured on either 200 mm wafers or 300 mm wafers.

Traceability

The devices manufactured at the 300 mm wafer fabrication facility are identified with the letter "G," as shown in the following package topmark example:

Marking Diagram for 300 mm Wafer Fabrication Facility



Current devices from the 200 mm fabrication facility are marked with the fabrication site code "F."

Qualification Data

Qualification data for Spartan-3 devices manufactured at the UMC 300 mm wafer facility is available at: <https://secure.xilinx.com/webreg/clickthrough.do?cid=38042>.

Response

No response to this notification is required. Please contact your [Xilinx Sales Representative](#) if you have any questions regarding product availability. Requests for qualification data or additional information may be directed to [Xilinx Technical Support](#).

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
05/05/05	1.0	Initial release.
05/13/05	1.0.1	Minor editorial updates to Qualification Report.
10/08/09	1.0.2	Fixed broken link on Qualification Data section.

Disclaimer

THE XILINX HARDWARE FPGA AND CPLD DEVICES REFERRED TO HEREIN ("PRODUCTS") ARE SUBJECT TO THE TERMS AND CONDITIONS OF THE XILINX LIMITED WARRANTY WHICH CAN BE VIEWED AT <http://www.xilinx.com/warranty.htm>. THIS LIMITED WARRANTY DOES NOT EXTEND TO ANY USE OF PRODUCTS IN AN APPLICATION OR ENVIRONMENT THAT IS NOT WITHIN THE SPECIFICATIONS STATED ON THE XILINX DATA SHEET. ALL SPECIFICATIONS ARE SUBJECT TO CHANGE WITHOUT NOTICE. PRODUCTS ARE NOT DESIGNED OR INTENDED TO BE FAIL-SAFE, OR FOR USE IN ANY APPLICATION REQUIRING FAIL-SAFE PERFORMANCE, SUCH AS LIFE-SUPPORT OR SAFETY DEVICES OR SYSTEMS, OR ANY OTHER APPLICATION THAT INVOKES THE POTENTIAL RISKS OF DEATH, PERSONAL INJURY OR PROPERTY OR ENVIRONMENTAL DAMAGE ("CRITICAL APPLICATIONS"). USE OF PRODUCTS IN CRITICAL APPLICATIONS IS AT THE SOLE RISK OF CUSTOMER, SUBJECT TO APPLICABLE LAWS AND REGULATIONS. ALL SPECIFICATIONS ARE SUBJECT TO CHANGE WITHOUT NOTICE.